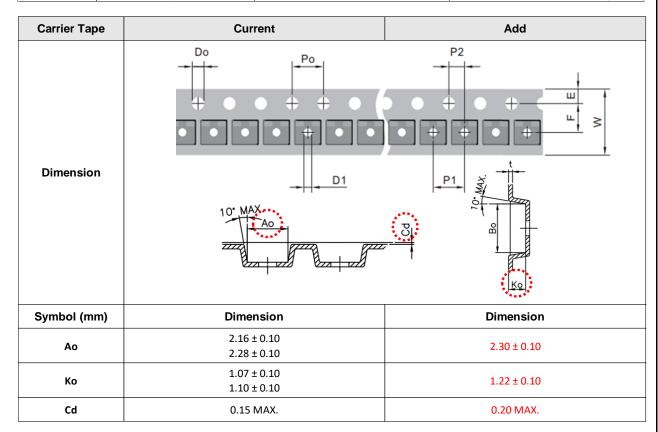
PRODUCT / PROCESS CHANGE NOTIFICATION

Generic Copy
PCN#2211002 • DATE: 10 th November, 2022
PCN Subject: Additional Assembly Site for Package SOT-363
PCN Change Category:
■ Material ■ Process □ Datasheet/Specification
☐ Reliability
Others (Additional assembly site)
Description of Change Purpose or Reason:
This PCN is being issued to announce the qualification of PANJIT Semiconductor
(Xuzhou) Co., Ltd (located in Jiangsu Province, China) as an alternate assembly
and test site for SOT-363 selected products. The products that will be manufactured
from this new assembly/test site are form, fit, and function compatible with the
current qualified manufacturing sites. The qualification incorporates new bill of
material (BOM) sets including the utilization of High-Density Leadframe, the change
of wire type and wire diameter. For more detail, please check below change
information.
We recommend that you acknowledge receipt of this notification within 30 days of

this PCN date. If you require samples for further evaluation, please feel free to contact your local sales representative and make a request. We are always pleased to serve you at any time.

• Change Information:

		Current	Add		
Assembly Site			PANJIT International Inc.	PANJIT Semiconductor (Xuzhou) Co., Ltd	
Location		Kaohsiung, Taiwan	Xuzhou, China		
Material	Wire	Material / Diameter (mil)	Au / 1.0 Cu / 1.0	Cu / 0.8	
	Epoxy Molding Compound	Product Name	ELER-8-500C-84	GR640HV-L1 B18	
	Carrier Tape	Material	Polycarbonate (PC)	Polystyrene (PS)	
	Ending Tape	Material	Polyester	Paper	
		Color	Black	Yellow	
Method	Process	De-Flash	Electrolytic De-flash	Chemical De-flash	
Form Marking Format		8KDH	M7QK 2.2.3.3.4.4.4.4.4.4.4.4.4.4.4.4.4.4.4.4.		



• Verification /Qualification Data:

The electrical characterization and high reliability testing have been completed on representative part numbers to ensure there is no change to device functionality or electrical specifications in the datasheet. There will be no change to the Form, Fit, or Function of products affected unless specifically indicated.

• Affected Product Type:

Function: MOSFET	
2N7002KDW	

• Effective Date: 10th February, 2023

The reliability test results are summarized below:

Product reliability test result: PASS

No.	DESCRIPTION	TEST CONDITION	DURATION	FAILURE RATE	
1	Temperature Cycling (TCT)	Ta = -55°C ~ +150°C (2 cycles / Hour)	1000 CYCLES	0/77 PCS	3 LOTS PASS
2	High Temperature Storage Test (HTSL)	Ta = 150°C	1000 HOURS	0/77 PCS	3 LOTS PASS
3	Resistance to Solder Heat (RSH)	Temperature of solder pot = 260 ±5°C Time for dipping in solder = 10 +2/-0 Sec	1 CYCLE	0/30 PCS	3 LOTS PASS
4	Solder ability (SD)	Temperature of solder pot = 245 ±5°C Time for dipping in solder = 5 ±0.5 Sec	1 CYCLE	0/10 PCS	3 LOTS PASS
5	Intermittent Forward Operation Life (IFOL)	△Tj≧100°C Power On: 120 sec Power Off: 120 sec	15000 CYCLES	0/77 PCS	3 LOTS PASS
6	High Temperature Reverse Bias (HTRB)	Ta = 150°C , VR = 80%VB, DC supply	1000 HOURS	0/77 PCS	3 LOTS PASS
7	High Temperature Gate Bias (HTGB)	Tj≦Tj max, 100%VGS	1000 HOURS	0/77 PCS	3 LOTS PASS
8	Autoclave (AC)	Ta = 121°C, P = 29.7psia ,100%RH	96 HOURS	0/77 PCS	3 LOTS PASS
9	Temperature Humidity Storage (THS)	Ta = 85°C , RH = 85%	1000 HOURS	0/77 PCS	3 LOTS PASS

• ELECTRICAL CHARACTERISTICS SUMMARY:

There is no change to the product electrical specifications.

• SAMPLES NEED:

Contact your local PANJIT sales representative.

• TECHNICAL CONTACT:

E-mail: alanliu@panjit.com.tw

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local PANJIT sales representative.

• ADDITIONAL RELIABILITY:

Contact your local PANJIT sales representative.

• CHANGED PART IDENTIFICATION:

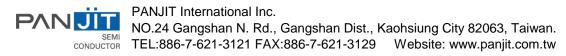
The tracking of 1st delivery after change can be identified by production lot number. Please contact your local sales for tracking lot number.

Please refer to below Lot number rule:

Lot number: 2924XXXXX.

1st digit "2" denotes Year 2022. 2nd digit "9" denotes September. 3rd and 4th digits denote Day.

From 5th digits (XXXXX) denotes production serial number.



Customer Acknowledgement Form

and agreed with this Process Change Notification.